

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Nishant Sinha

**Serial No.:** 10/668,914

**Filed:** September 23, 2003

**For:** PROCESS AND INTEGRATION  
SCHEME FOR FABRICATING  
CONDUCTIVE COMPONENTS,  
THROUGH-VIAS AND  
SEMICONDUCTOR COMPONENTS  
INCLUDING CONDUCTIVE THROUGH-  
WAFER VIAS

**Confirmation No.:** 2525

**Examiner:** W. Lindsay Jr.

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-5859US  
(02-0390.00/US)

**Notice of Allowance Mailed:**

March 22, 2007

**VIA ELECTRONIC FILING  
JUNE 20, 2007**

**COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

These Comments follow the Notice of Allowance of March 22, 2007, and set forth Applicant's comments, pursuant to 37 C.F.R. § 1.104(e), on the statement of reasons for

allowance that accompanied Office Actions of June 9, 2006 and November 20, 2006.

In the Office Action of June 9, 2006, it was indicated that:

the prior art, either singly or in combination fails to anticipate or render obvious, the limitations of:

...an insulative layer located between the annular conductive layer and the substrate, as required by claim 31, as it depends from claim 25; and

...a barrier layer on the first surface, as required by claims 32 and 66.

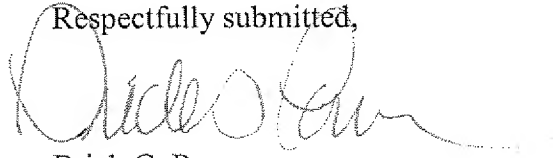
The Office Action of November 20, 2006, provided:

the prior art, either singly or in combination fails to anticipate or render obvious, the limitations of:

...at least one via extending into the first surface of the substrate and terminating short of the opposing, second surface and including a seed layer comprising conductive material at least partially over a surface of the aperture, an annular conductive layer contacting the seed layer, and a filler material occupying a remainder of the via, the filler material circumscribed by and contacting the annular conductive layer, as required by claim 25.

While the stated reasons for allowance comprise a summary of subject matter recited in various claims of the above-referenced application, the scope of each claim is based on its actual language and the full scope of equivalents available to each element of recited subject matter.

Respectfully submitted,

A handwritten signature in dark ink, appearing to read "Brick G. Power", written over a horizontal line.

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Date: June 20, 2007

BGP/ps:eg

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